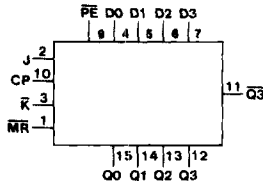


High-Speed CMOS Logic

4-Bit Parallel Access Register



FUNCTIONAL DIAGRAM

Type Features:

- Asynchronous Master Reset
- J, \bar{K} , (D) inputs to first stage
- Fully synchronous serial or parallel data transfer
- Shift right and parallel load capability
- Complementary output from last stage
- Buffered inputs
- Typical $f_{MAX}=50$ MHz @ $V_{CC}=5$ V, $C_L=15$ pF, $T_A=25^\circ$ C

Family Features:

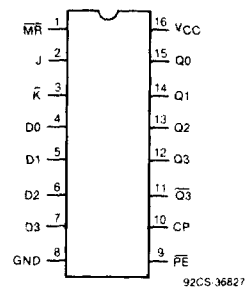
- Fanout (Over Temperature Range):
Standard Outputs - 10 LSTTL Loads
Bus Driver Outputs - 15 LSTTL Loads
- Wide Operating Temperature Range:
CD74HC/HCT: -40 to $+85^\circ$ C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- Alternate Source is Philips/Signetics
- CD54HC/CD74HC Types:
2 to 6 V Operation
High Noise Immunity: $N_{IL}=30\%$, $N_{IH}=30\%$ of V_{CC}
@ $V_{CC}=5$ V
- CD54HCT/CD74HCT Types:
4.5 to 5.5 V Operation
Direct LSTTL Input Logic Compatibility
 $V_{IL}=0.8$ V Max., $V_{IH}=2$ V Min.
CMOS Input Compatibility
 $I_i \leq 1 \mu A$ @ V_{OL} , V_{OH}

The functional characteristics of the RCA-CD54/74HC195 and CD54/74HCT195 4-Bit Parallel Access Register are indicated in the Logic Diagram and Function Table. The device is useful in a wide variety of shifting, counting and storage applications. It performs serial, parallel, serial-to-parallel, or parallel-to-serial data transfers at very high speeds.

The two modes of operation, shift right (Q0-Q1) and parallel load, are controlled by the state of the Parallel Enable (PE) input. Serial data enters the first flip-flop (Q0) via the J and \bar{K} inputs when the PE input is high, and is shifted one bit in the direction Q0-Q1-Q2-Q3 following each LOW-to-HIGH clock transition. The J and \bar{K} inputs provide the flexibility of the JK-type input for special applications and, by tying the two pins together, the simple D-type input for general applications. The device appears as four common-clocked D flip-flops when the PE input is LOW. After the LOW-to-HIGH clock transition, data on the parallel inputs (D0-D3) is transferred to the respective Q0-Q3 outputs. Shift left operation (Q3-Q2) can be achieved by tying the Qn outputs to the Dn-1 inputs and holding the PE input low.

All parallel and serial data transfers are synchronous, occurring after each LOW-to-HIGH clock transition. The HC/HCT195 series utilizes edge-triggering; therefore, there is no restriction on the activity of the J, \bar{K} , Pn and PE inputs for logic operations, other than the set-up and hold time requirements. A LOW on the asynchronous Master Reset (\bar{MR}) input sets all Q outputs LOW, independent of any other input condition.

The CD54HC195 and CD54HCT195 are supplied in 16-lead hermetic dual-in-line ceramic packages (F suffix). The CD74HC195 and CD74HCT195 are supplied in 16-lead dual-in-line plastic packages (E suffix) and in 16-lead dual-in-line surface mount plastic package (M suffix). Both types are also available in chip form (H suffix).



TERMINAL ASSIGNMENT

CD54/74HC195 CD54/74HCT195

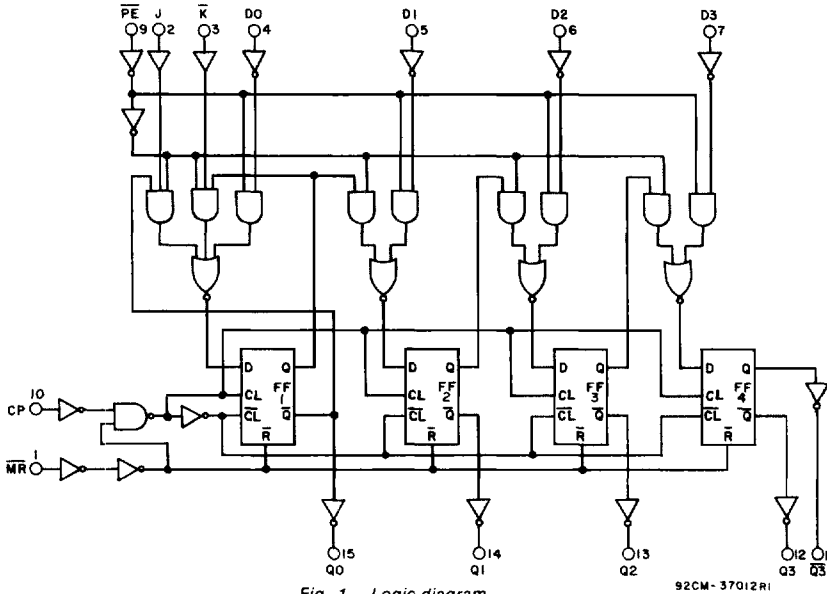


Fig. 1 - Logic diagram.

Function Table

Operating Modes	INPUTS						OUTPUTS				
	MR	CP	PE	J	K	D _n	Q0	Q1	Q2	Q3	Q3̄
Asynchronous Reset	L	X	X	X	X	X	L	L	L	L	H
Shift, Set first stage	H	↗	h	h	h	X	H	q ₀	q ₁	q ₂	q̄ ₂
Shift, Reset first stage	H	↗	h	l	l	X	L	q ₀	q ₁	q ₂	q̄ ₂
Shift, Toggle first stage	H	↗	h	h	l	X	q̄ ₀	q ₀	q ₁	q ₂	q̄ ₂
Shift, Retain first stage	H	↗	h	l	h	X	q ₀	q ₀	q ₁	q ₂	q̄ ₂
Parallel Load	H	↗	l	X	X	d _n	d ₀	d ₁	d ₂	d ₃	d̄ ₃

H=HIGH voltage level.

L=LOW voltage level.

X=Don't care.

l=LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition.

h=HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition.

d_n (q_n)=Lower case letters indicate the state of the referenced input (or output) one set-up time prior to the LOW-to-HIGH clock transition.

↗=LOW-to-HIGH clock transition.

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE, (V_{CC}):

(Voltages referenced to ground) -0.5 to + 7 V

DC INPUT DIODE CURRENT, I_{IK} (FOR V_i < -0.5 V OR V_i > V_{CC} + 0.5 V) ±20mA

DC OUTPUT DIODE CURRENT, I_{OK} (FOR V_o < -0.5 V OR V_o > V_{CC} + 0.5 V) ±20mA

DC DRAIN CURRENT, PER OUTPUT (I_O) (FOR -0.5 V < V_o < V_{CC} + 0.5 V) ±25mA

DC V_{CC} OR GROUND CURRENT (I_{CC}) ±50mA

POWER DISSIPATION PER PACKAGE (P_D):

For T_A = -40 to +60°C (PACKAGE TYPE E) 500 mW

For T_A = +60 to +85°C (PACKAGE TYPE E) Derate Linearly at 8 mW/°C to 300 mW

For T_A = -55 to +100°C (PACKAGE TYPE F, H) 500 mW

For T_A = +100 to +125°C (PACKAGE TYPE F, H) Derate Linearly at 8 mW/°C to 300 mW

For T_A = -40 to +70°C (PACKAGE TYPE M) 400 mW

For T_A = +70 to +125°C (PACKAGE TYPE M) Derate Linearly at 6 mW/°C to 70 mW

OPERATING-TEMPERATURE RANGE (T_A):

PACKAGE TYPE F, H -55 to +125°C

PACKAGE TYPE E, M -40 to +85°C

STORAGE TEMPERATURE (T_{stg}) -65 to +150°C

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 ± 1/32 in. (1.59 ± 0.79 mm) from case for 10 s max. +265°C

Unit inserted into a PC Board (min. thickness 1/16 in., 1.59 mm)

with solder contacting lead tips only +300°C

CD54/74HC195 CD54/74HCT195

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CD74HC195/CD54HC195									CD74HCT195/CD54HCT195									UNITS					
	TEST CONDITIONS			74HC/54HC TYPES			74HC TYPES			54HC TYPES			TEST CONDITIONS		74HCT/54HCT TYPES			74HCT TYPES			54HCT TYPES			
	V _I V	I _O mA	V _{CC} V	+25°C			-40/ +85°C			-55/ +125°C			V _I V	V _{CC} V	+25°C			-40/ +85°C			-55/ +125°C			
				Min	Typ	Max	Min	Max	Min	Max	Min	Max			Min	Typ	Max	Min		Max	Min	Max		
High-Level Input Voltage V _{IH}			2	1.5	—	—	1.5	—	1.5	—	—	—	4.5		2	—	—	2	—	2	—	—	V	
			4.5	3.15	—	—	3.15	—	3.15	—	—	—	to		—	—	—	—	—	—	—	—		
			6	4.2	—	—	4.2	—	4.2	—	—	—	5.5		—	—	—	—	—	—	—	—		
Low-Level Input Voltage V _{IL}			2	—	—	0.5	—	0.5	—	0.5	—	—	4.5		—	—	0.8	—	0.8	—	0.8	—	V	
			4.5	—	—	1.35	—	1.35	—	1.35	—	—	to		—	—	—	—	—	—	—	—		
			6	—	—	1.8	—	1.8	—	1.8	—	—	5.5		—	—	—	—	—	—	—	—		
High-Level Output Voltage V _{OH}	V _{IL}	-0.02	2	1.9	—	—	1.9	—	1.9	—	—	V _{IL}		4.5	4.4	—	—	4.4	—	4.4	—	—	V	
or			4.5	4.4	—	—	4.4	—	4.4	—	—	or		4.5	—	—	—	—	—	—	—	—		
CMOS Loads	V _{IH}		6	5.9	—	—	5.9	—	5.9	—	—	V _{IH}		—	—	—	—	—	—	—	—	—		
TTL Loads	V _{IL}										V _{IL}		4.5	3.98	—	—	3.84	—	—	3.7	—	—	V	
or		-4	4.5	3.98	—	—	3.84	—	3.7	—	or		4.5	—	—	—	—	—	—	—	—	—		
V _{IH}		-5.2	6	5.48	—	—	5.34	—	5.2	—	V _{IH}		—	—	—	—	—	—	—	—	—	—		
Low-Level Output Voltage V _{OL}	V _{IL}	0.02	2	—	—	0.1	—	0.1	—	0.1	—	V _{IL}		4.5	—	—	0.1	—	0.1	—	0.1	—	V	
or			4.5	—	—	0.1	—	0.1	—	0.1	—	or		—	—	—	—	—	—	—	—	—		
CMOS Loads	V _{IH}		6	—	—	0.1	—	0.1	—	0.1	—	V _{IH}		—	—	—	—	—	—	—	—	—	—	
TTL Loads	V _{IL}										V _{IL}		4.5	—	—	0.26	—	0.33	—	0.4	—	—	V	
or		4	4.5	—	—	0.26	—	0.33	—	0.4	or		4.5	—	—	—	—	—	—	—	—	—		
V _{IH}		5.2	6	—	—	0.26	—	0.33	—	0.4	V _{IH}		—	—	—	—	—	—	—	—	—	—		
Input Leakage Current I _I	V _{CC}		6	—	—	±0.1	—	±1	—	±1	—	Any Voltage Between V _{CC} & Gnd	5.5	—	—	±0.1	—	±1	—	±1	—	—	μA	
or	Gnd		—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—		
Quiescent Device Current I _{CC}	V _{CC}		0	6	—	—	8	—	80	—	160	V _{CC}	5.5	—	—	8	—	80	—	160	—	—	μA	
or	Gnd		—	—	—	—	—	—	—	—	—	or	—	—	—	—	—	—	—	—	—	—		
Additional Quiescent Device Current per input pin: 1 unit load ΔI _{CC} *												V _{CC} -2.1	4.5	—	—	100	360	—	450	—	490	—	μA	
												5.5	—	—	—	—	—	—	—	—	—	—		

*For dual-supply systems theoretical worst case (V_I = 2.4 V, V_{CC} = 5.5 V) specification is 1.8 mA.

HCT Input Loading Table

Input	Unit Loads*
D0-D3	0.3
PE	0.65
MR	0.3
CP	0.3
J, K	0.3

*Unit Load is ΔI_{CC} limit specified in Static Characteristic Chart, e.g., 360 μA max. @ 25°C.

CD54/74HC195 CD54/74HCT195

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For T _A =Full Package Temperature Range) V _{CC} *			
CD54/74HC Types	2	6	V
CD54/74HCT Types	4.5	5.5	V
DC Input or Output Voltage V _{in} , V _{out}	0	V _{CC}	V
Operating Temperature T _A :			
CD74 Types	-40	+85	°C
CD54 Types	-55	+125	°C
Input Rise and Fall Times t _r , t _f			
at 2 V	0	1000	ns
at 4.5 V	0	500	ns
at 6 V	0	400	ns

*Unless otherwise specified, all voltages are referenced to Ground.

SWITCHING CHARACTERISTICS (V_{CC} = 5 V, T_A = 25° C, Input t_r, t_f = 6 ns)

CHARACTERISTIC	SYMBOL	C _L pF	Typical		Units
			HC	HCT	
CP to Qn Propagation Delay	t _{PHL} t _{PLH}	15	14	14	ns
MR to Qn	t _{PHL}	15	13	14	ns
Maximum Clock Frequency	f _{MAX}	15	50	50	MHz
Power Dissipation Capacitance*	C _{PD}	—	45	50	pF

*C_{PD} is used to determine the dynamic power consumption, per register.

$$PD = C_{PD} V_{CC}^2 f_i + \sum C_L V_{CC}^2 f_o \text{ where}$$

f_i = input frequency

f_o = output frequency

C_L = output load capacitance

V_{CC} = supply voltage.

CD54/74HC195
CD54/74HCT195

Pre-requisite for Switching Function

CHARACTERISTIC	SYMBOL	V _{CC}	25° C				-40° C to +85° C				-55° C to +125° C				UNITS
			HC		HCT		74HC		74HCT		54HC		54HCT		
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Clock Frequency (Figure 3)	f _{MAX}	2	6	—	—	5	—	—	—	4	—	—	—	ns	
		4.5	30	—	25	—	25	—	20	—	20	—	16		
		6	35	—	—	29	—	—	—	23	—	—	—		
MR Pulse Width (Figure 3)	t _w	2	80	—	—	100	—	—	—	120	—	—	—	ns	
		4.5	16	—	20	—	20	—	25	—	24	—	30		
		6	14	—	—	17	—	—	—	20	—	—	—		
Clock Pulse Width (Figure 3)	t _w	2	80	—	—	100	—	—	—	120	—	—	—	ns	
		4.5	16	—	20	—	20	—	25	—	24	—	30		
		6	14	—	—	17	—	—	—	20	—	—	—		
Set-up Time J, \overline{K} , \overline{PE} to Clock (Figure 5)	t _{SU}	2	100	—	—	125	—	—	—	150	—	—	—	ns	
		4.5	20	—	20	—	25	—	25	—	30	—	30		
		6	17	—	—	21	—	—	—	26	—	—	—		
Hold Time J, \overline{K} , \overline{PE} to Clock (Figure 5)	t _H	2	3	—	—	3	—	—	—	3	—	—	—	ns	
		4.5	3	—	3	—	3	—	3	—	3	—	3		
		6	3	—	—	3	—	—	—	3	—	—	—		
Removal Time MR to Clock (Figure 3)	t _{REM}	2	80	—	—	100	—	—	—	120	—	—	—	ns	
		4.5	16	—	16	—	20	—	20	—	24	—	24		
		6	14	—	—	17	—	—	—	20	—	—	—		

SWITCHING CHARACTERISTICS (C_L=50 pF, Input t_r,t_f=6 ns)

CHARACTERISTIC	SYMBOL	V _{CC}	25° C				-40° C to +85° C				-55° C to +125° C				UNITS
			HC		HCT		74HC		74HCT		54HC		54HCT		
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Propagation Delay CP to Output (Figure 3)	t _{PLH}	2	—	175	—	—	—	220	—	—	—	265	—	—	ns
		4.5	—	35	—	35	—	44	—	44	—	53	—	53	
		6	—	30	—	—	—	37	—	—	—	45	—	—	
Propagation Delay MR to Output (Figure 3)	t _{PLH}	2	—	150	—	—	—	190	—	—	—	225	—	—	ns
		4.5	—	30	—	35	—	38	—	44	—	45	—	53	
		6	—	26	—	—	—	33	—	—	—	38	—	—	
Output Transition Time	t _{TLH} t _{THL}	2	—	75	—	—	—	95	—	—	—	110	—	—	ns
		4.5	—	15	—	15	—	19	—	19	—	22	—	22	
		6	—	13	—	—	—	16	—	—	—	19	—	—	
Input Capacitance	C _i		—	10	—	10	—	10	—	10	—	10	—	pF	

CD54/74HC195 CD54/74HCT195

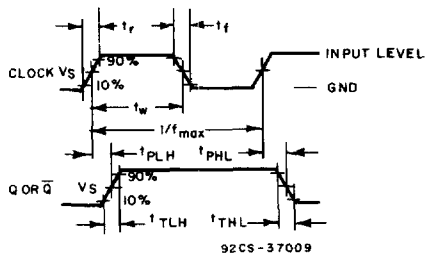


Fig. 3 - Clock pre-requisite and propagation delays and output transition times.

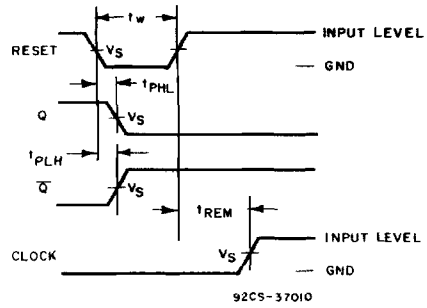


Fig. 4 - Master Reset pre-requisite and propagation delays.

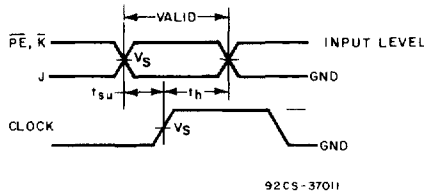


Fig. 5 - J, \bar{K} or Parallel Enable pre-requisite times.

	HC	HCT
INPUT LEVEL	V_{CC}	3V
V_s	50%	1.3V